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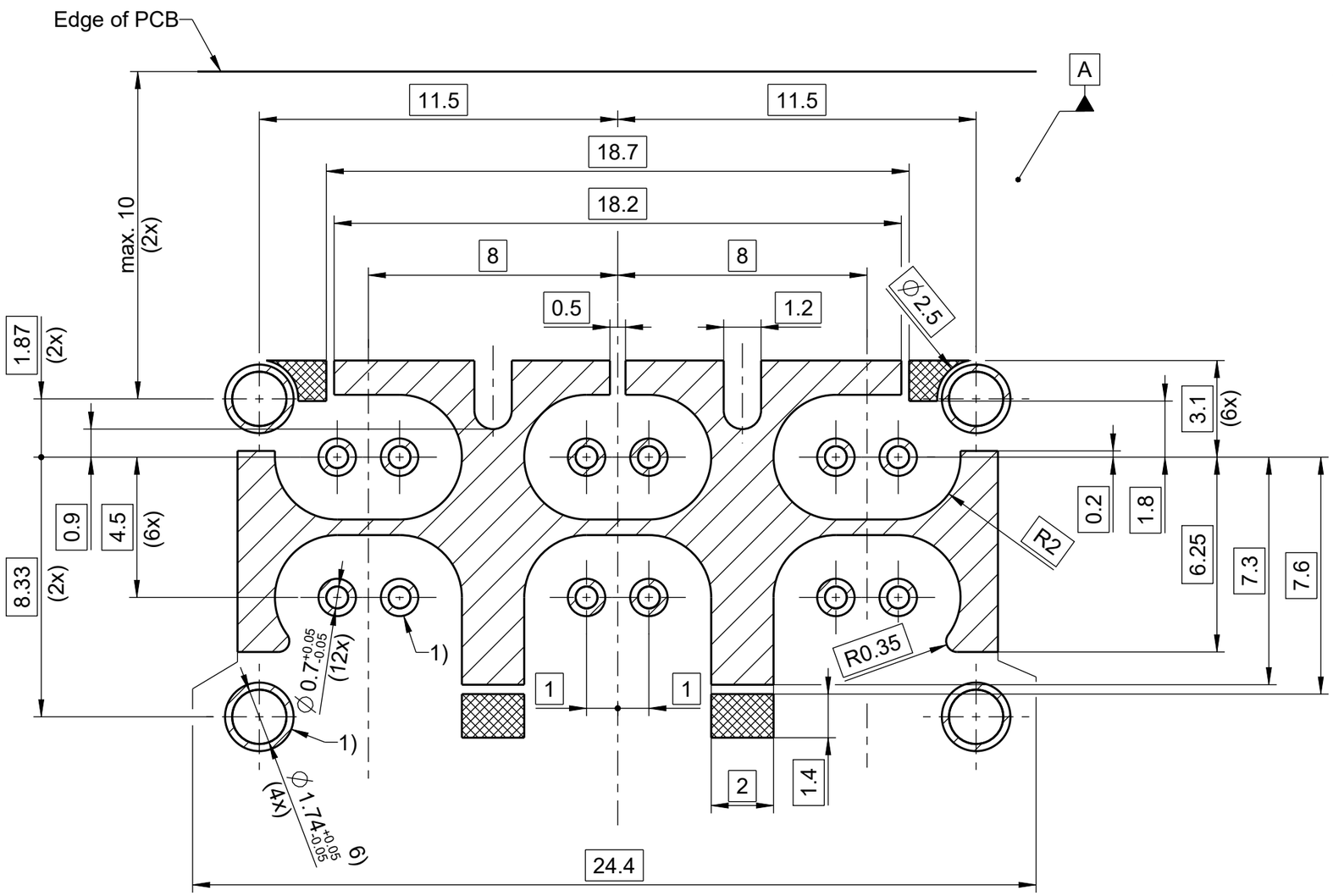
VORSERIE
PRE-SERIES

1) Pad width min. 0.2mm
2) Thickness fo soldering paste min. 0.1mm
3) All drill holes plated inclusive pads on the backside
4) All through holes ⌖ | ∅0.05 Ⓜ | A
5) Solder area and keep-out area ⌓ | 0.2 | A | B-B
6) For existing boards ∅1.62±0.05 is still useable. Do not use for new applications.

Solder area

Keepout area, free of solder



The stated dimensions are only recommendations.
A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.
Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimal placement of the connector.
In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

200	21-v362	M_Steinbach	25.08.2021
100	20-m799	T_Stockhamme	21.06.2021
rev.	*change-no*	*name*	*date*

Rosenberger

vertraulich / *confidential*

general tolerance ---

	date	*name*
drawn	07.05.2021	T_Stockhamme
check.	27.08.2021	F_Schnitzenb
appr.	03.11.2021	S_Mittermeie

dimensioning incl. plating

Size ISO 14405
Tolerancing ISO 8015

scale: 6:1 ( )
weight[g]: 14.088
surface[mm²]: 2356.9
material: ---
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title:
Leiterplatten-Layout
PCB layout

drawing-no.: MB_940
sheet: 1
of: 1

remarks: .

PD_FB_01
-METRIC-
ISO-Projektion Methode 1